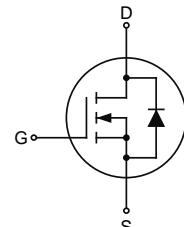


# N-Channel Enhancement Mode MOSFET

## 1. Product Information

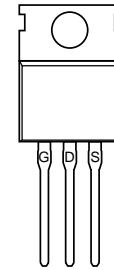
### 1.1 Features

- Spilt Gate Trench Technology
- Excellent  $R_{DS(ON)}$
- Low gate charge



### 1.2 Applications

- DC-DC Converter
- Load Switch for Portable Device
- Battery Switch
- Rectifier



Top View  
TO-220

### 1.3 Quick reference

- $BV \geq 100V$
- $I_D \leq 120A$
- $R_{DS(ON)} \leq 5.4m\Omega @ V_{GS} = 10V$  (Type: 4.5m $\Omega$ )

## 2. Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape width	Quantity
KJ053N10C	TO-220	<b>053N10</b> YWWXXX Date Code	-	-	1000

## 3. Absolute Maximum Ratings ( $T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current $V_{GS} @ 10V$	120	A
$I_D @ T_A=100^\circ C$	Continuous Drain Current $V_{GS} @ 10V$	84	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	440	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>2</sup>	225	mJ
$P_D$	Power Dissipation	192	W
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	-55~150	°C
$R_{\theta JC}$	Thermal Resistance Junction-Case	0.65	°C/W

#### 4. Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise specified)

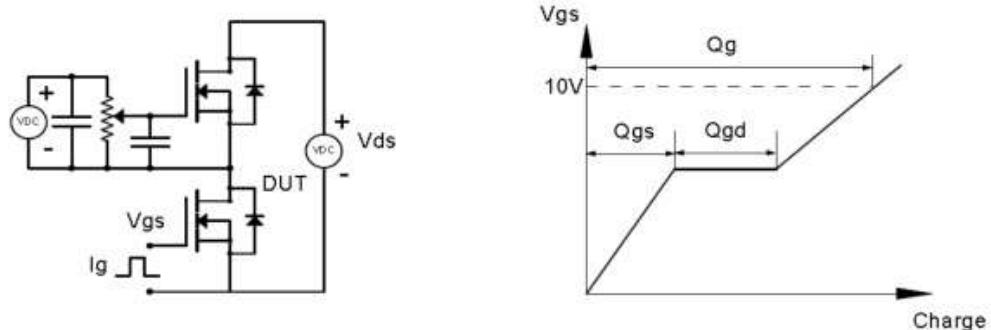
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100	-	-	V
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage <sup>3</sup>	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=250\mu\text{A}$	2.0	3.0	4.0	V
$I_{\text{DSS}}$	Zero Gate Voltage Source Current	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	-	4.5	5.4	$\text{m}\Omega$
$R_{\text{G}}$	Gate Resistance	Frequency=1.0MHz	-	3.5	-	$\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}$ Frequency=1MHz	-	3244	-	pF
$C_{\text{oss}}$	Output Capacitance		-	1075	-	
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	52	-	
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=50\text{V}, R_{\text{L}}=2.5\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=6\Omega$	-	22	-	ns
$t_{\text{r}}$	Turn-on Rise Time		-	36	-	
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	49	-	
$t_{\text{f}}$	Turn-off Fall Time		-	31	-	
$Q_{\text{g}}$	Total Gate Charge	$V_{\text{DS}}=50\text{V}, I_{\text{DS}}=20\text{A}$ $V_{\text{GS}}=10\text{V}$	-	51	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	15	-	
$Q_{\text{gd}}$	Gate-Drain Charge		-	13	-	
<b>Source-Drain Diode Characteristics</b>						
$V_{\text{DS}}$	Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=20\text{A}$	-	-	1.2	V
$I_{\text{S}}$	Diode Forward Current <sup>4</sup>		-	-	120	A
$t_{\text{rr}}$	Reverse Recovery Time	$I_{\text{S}}=15\text{A}, V_{\text{GS}}=0\text{V}$ $dI_{\text{F}}/dt=100\text{A}/\mu\text{s}$	-	58	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge		-	90	-	nC

Notes:

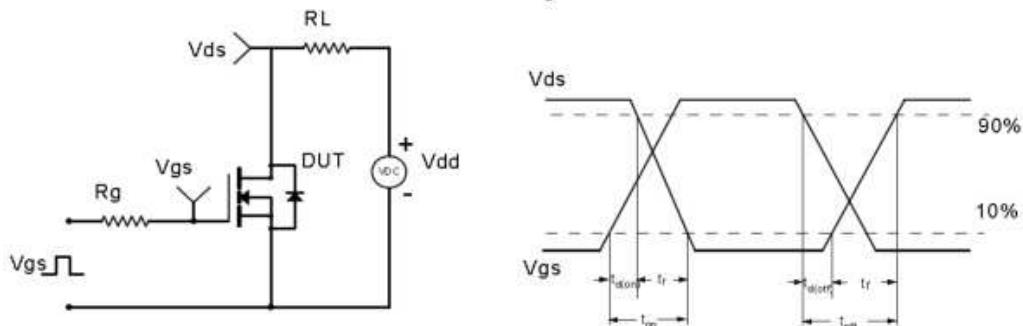
1. Repetitive Rating: pulse width limited by maximum junction temperature
2. E<sub>AS</sub> condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=50\text{V}$ ,  $R_G=25\Omega$ ,  $L=0.5\text{mH}$
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$
4. Surface Mounted on FR-4 Board,  $t \leq 10 \text{ sec}$

## 5. Test Circuit & Waveform

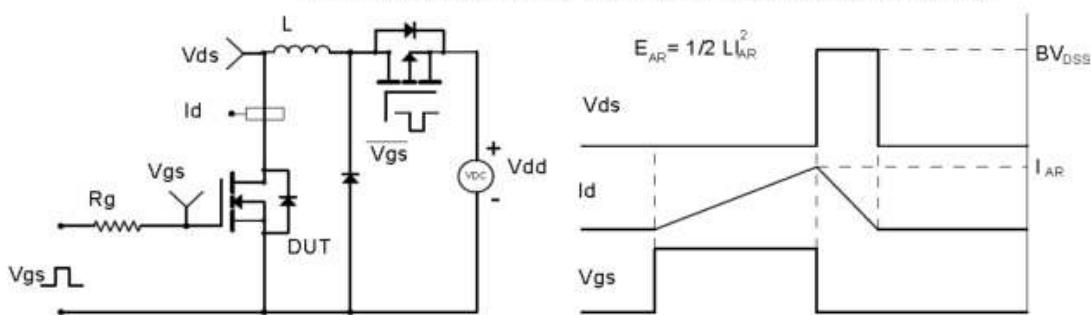
Gate Charge Test Circuit & Waveform



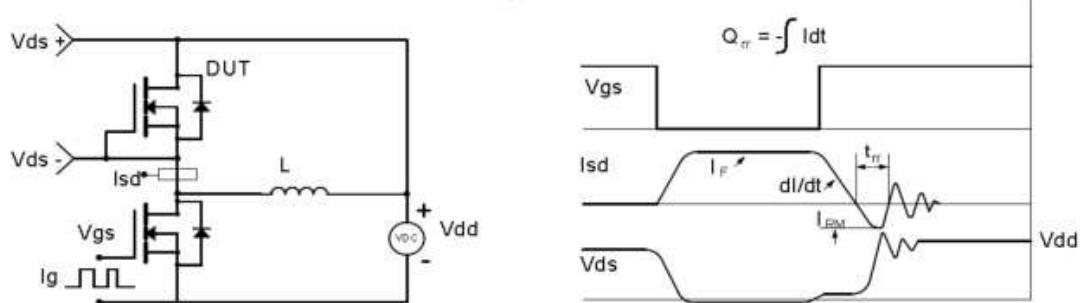
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



## 6. Typical Characteristics

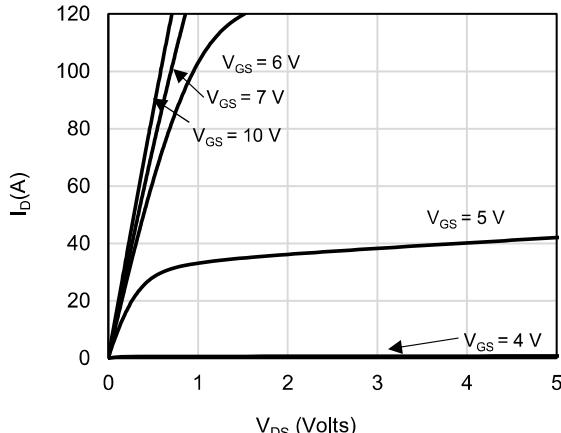


Figure 1: On-Region Characteristics

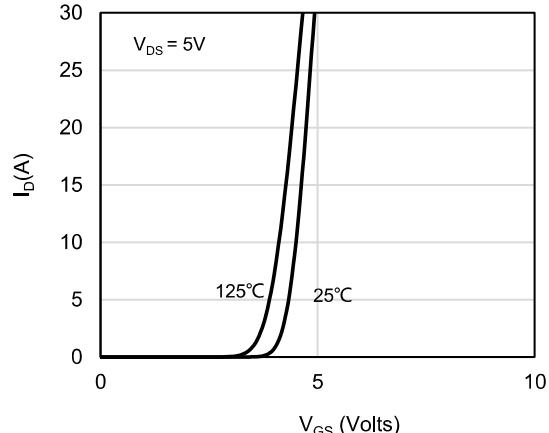


Figure 2: Transfer Characteristics

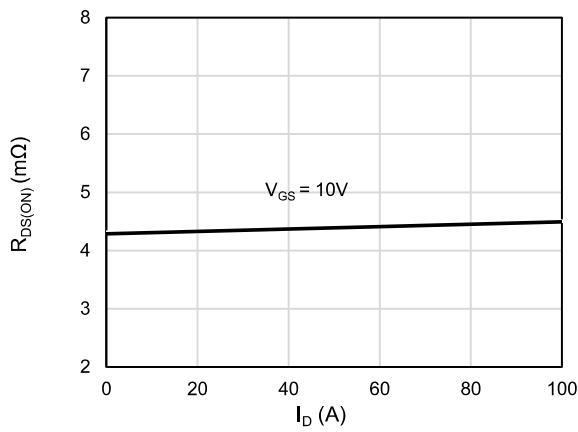


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

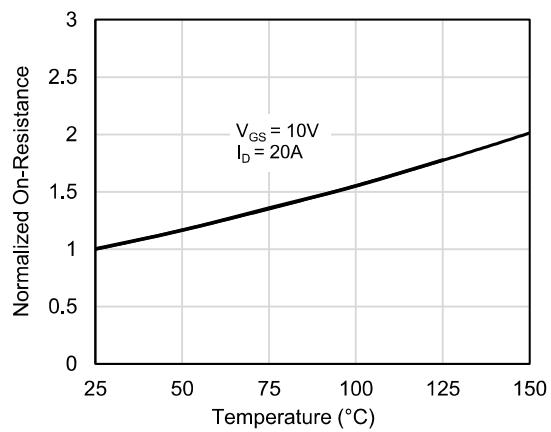


Figure 4: On-Resistance vs. Junction Temperature

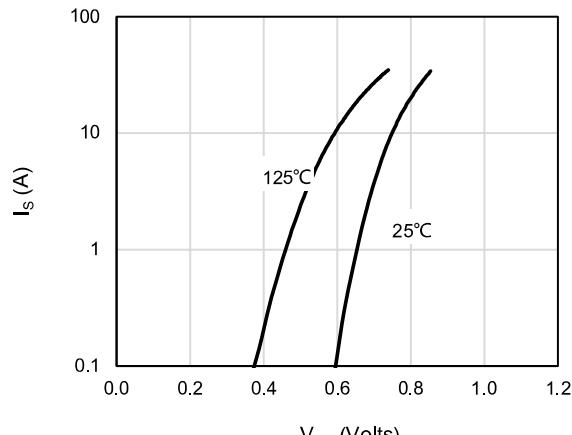


Figure 5: Body-Diode Characteristics

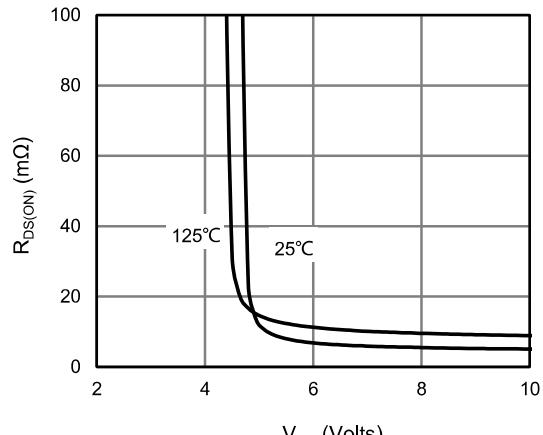
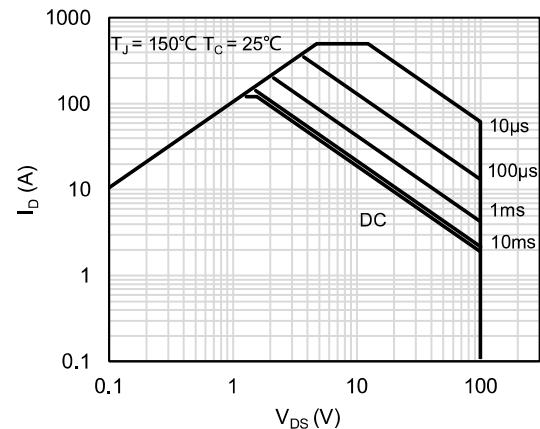
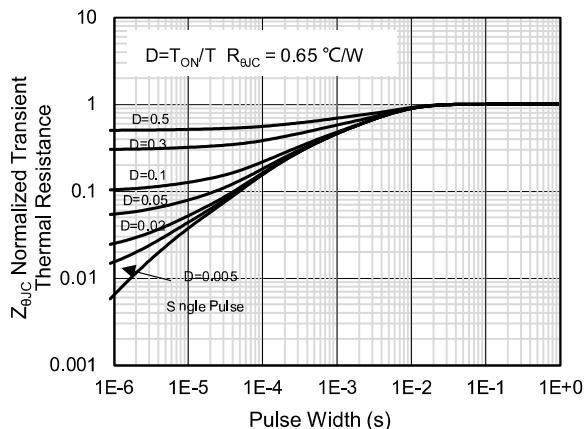
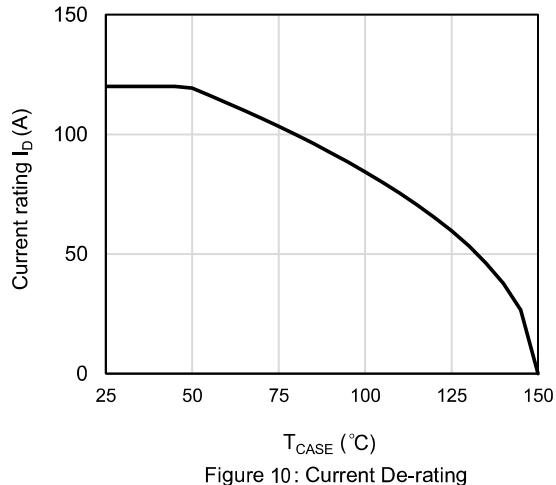
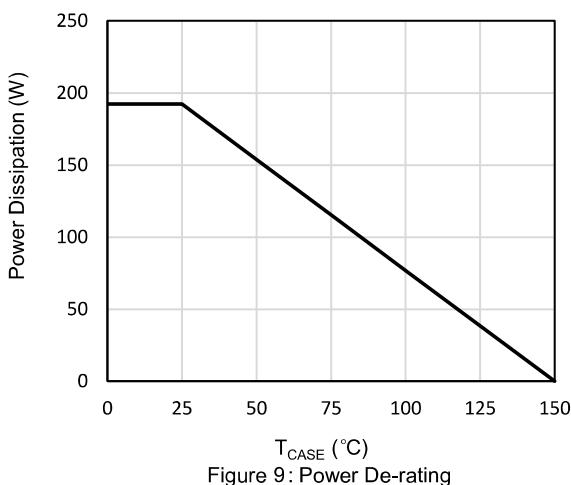
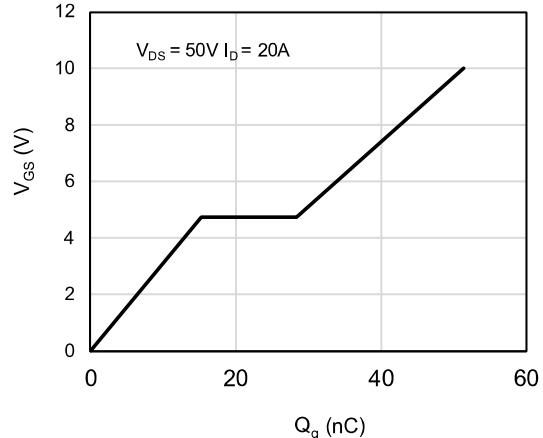
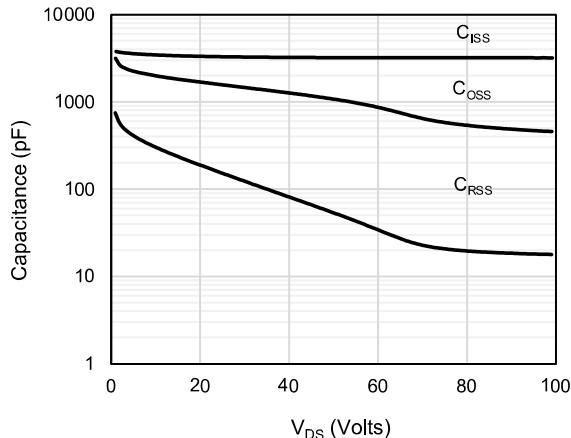


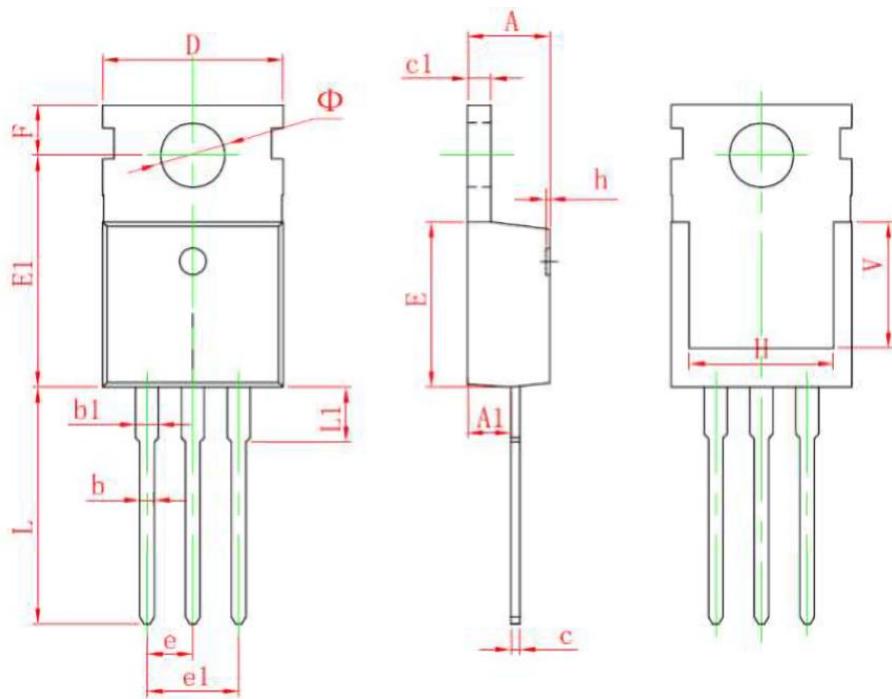
Figure 6: On-Resistance vs. Gate-Source Voltage

## 6. Typical Characteristics (cont.)



## 7. Package Dimensions

### TO-220 Package



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	13.050	0.498	0.514
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150